

Title (en)

LED MODULE, METHOD FOR PRODUCING THE SAME AND THE USE THEREOF

Title (de)

LED-MODUL, VERFAHREN ZU DESSEN HERSTELLUNG UND DESSEN VERWENDUNG

Title (fr)

MODULE DEL, SON PROCEDE DE PRODUCTION ET SON UTILISATION

Publication

EP 1299910 A1 20030409 (DE)

Application

EP 01953900 A 20010710

Priority

- DE 0102565 W 20010710
- DE 10033502 A 20000710

Abstract (en)

[origin: WO0205357A1] The invention relates to an LED module comprising a substrate (1) with a good thermal conductivity, on whose surface one or more radiation-emitting semiconductor elements (2) is/are fixed and whose underside is fixed to a support body (3) with a high thermal capacity. The component fixing element (4) placed between the semiconductor elements (2) and the substrate (1) and the substrate fixing element (5) placed between the substrate (1) and the support body (3) have a good thermal conductivity. The invention also relates to a method for producing the LED module, according to which metal surfaces that are suitable for use as etching masks improve the application of the current required during anodic bonding and at the same time are used as contact surfaces for contacting the radiation-emitting semiconductor elements (2). The invention further relates to the use of the LED module. The advantage of said inventive LED module is that the semiconductor components can be supplied with a higher current, as a result of the high thermal capacity of the support body.

IPC 1-7

H01L 33/00; **H01L 25/075**; **H01L 25/13**; **F21V 29/00**

IPC 8 full level

F21K 99/00 (2010.01); **H01L 25/075** (2006.01); **H01L 25/13** (2006.01); **H01L 33/64** (2010.01); **H01L 33/62** (2010.01)

CPC (source: EP US)

H01L 25/0753 (2013.01 - EP US); **H01L 25/13** (2013.01 - EP US); **H01L 33/641** (2013.01 - EP US); **H01L 33/62** (2013.01 - EP US); **H01L 2224/48465** (2013.01 - EP US); **H01L 2924/01322** (2013.01 - EP US); **H01L 2924/10253** (2013.01 - EP US); **H01L 2924/3025** (2013.01 - EP US)

Citation (search report)

See references of WO 0205357A1

Designated contracting state (EPC)

AT DE

DOCDB simple family (publication)

WO 0205357 A1 20020117; DE 10033502 A1 20020131; EP 1299910 A1 20030409; US 2003142500 A1 20030731; US 6860621 B2 20050301

DOCDB simple family (application)

DE 0102565 W 20010710; DE 10033502 A 20000710; EP 01953900 A 20010710; US 34544203 A 20030110